

[illegible]

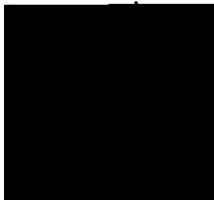


/ Descriptions

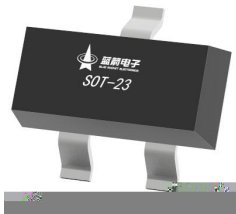
/ Features

/ Applications

/ Equivalent Circuit



/ Pinning



/ h_{FE} Classifications & Marking

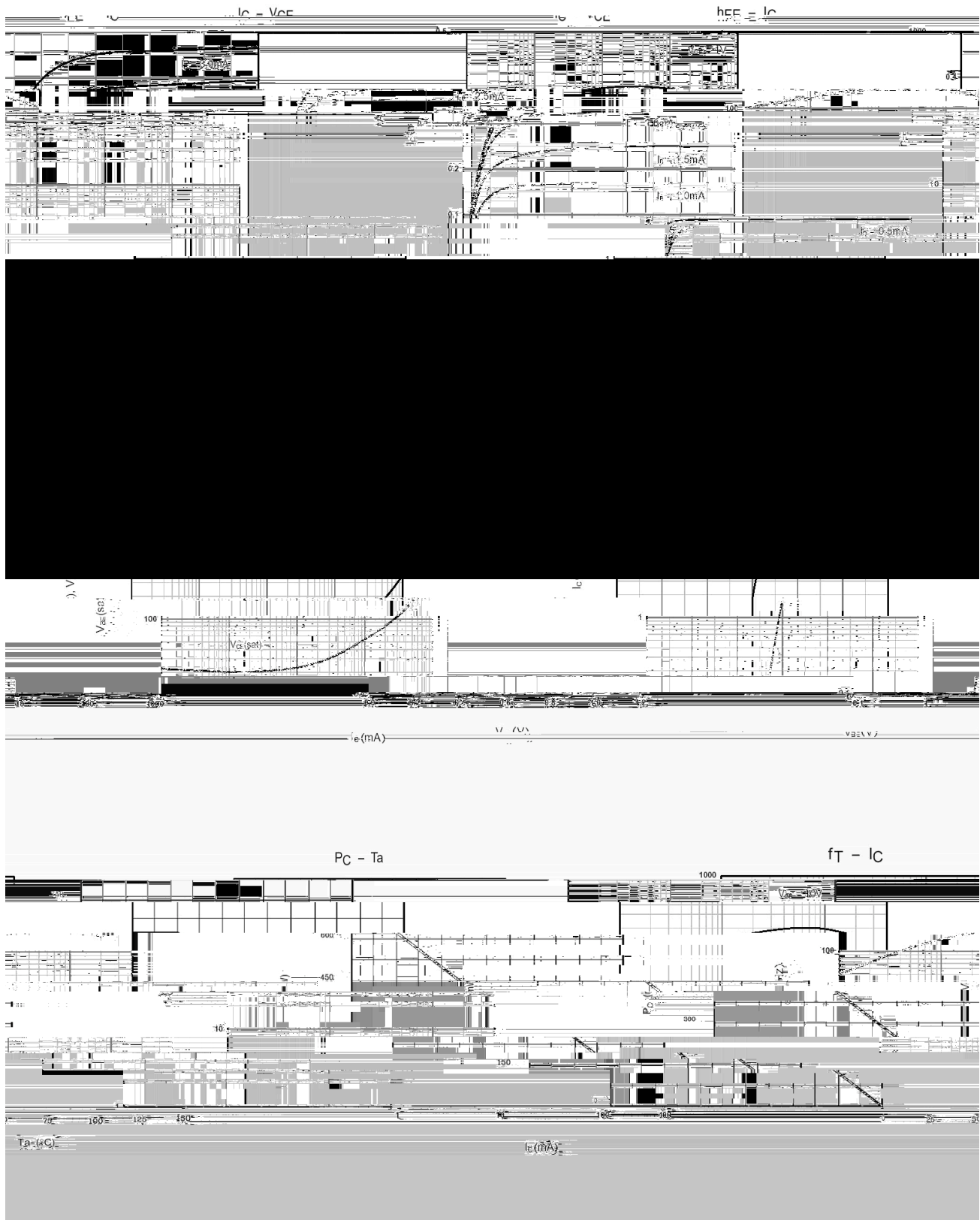


/ Absolute Maximum Ratings(Ta=25)

			℃
		~	℃

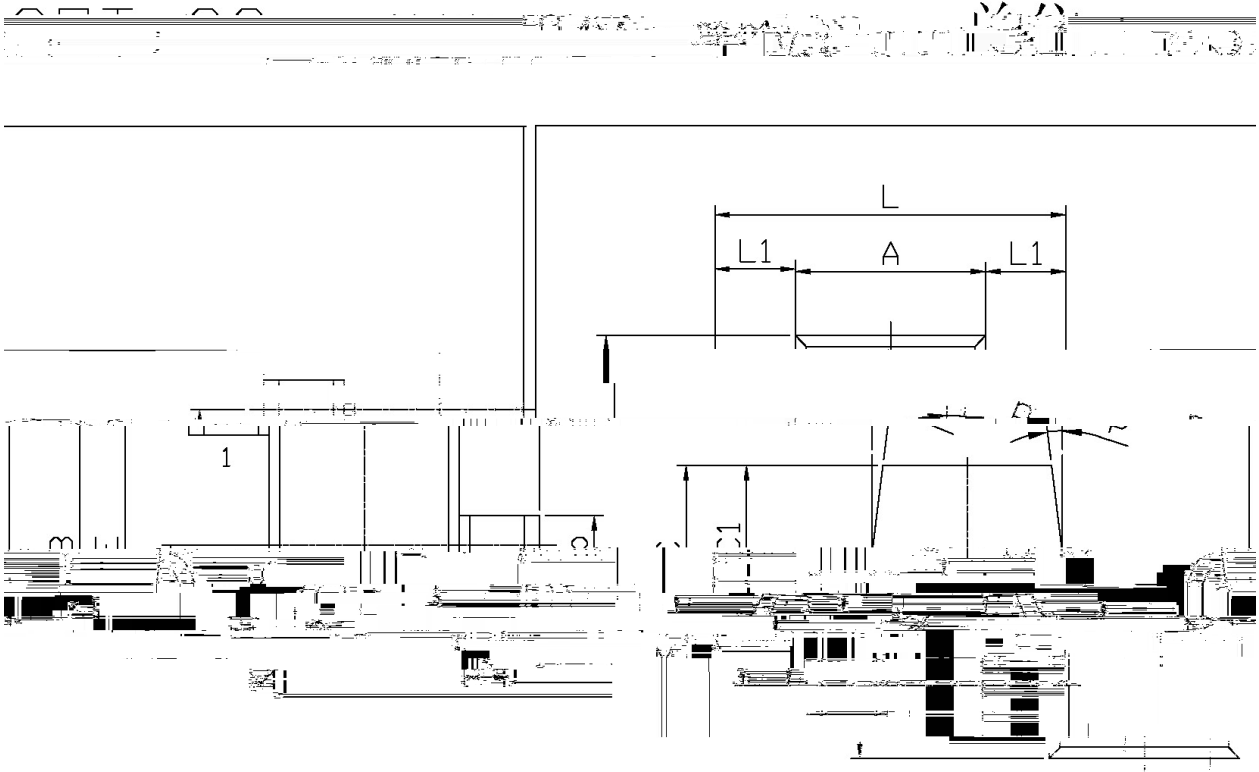
/ Electrical Characteristics(Ta=25)

/ Electrical Characteristic Curve





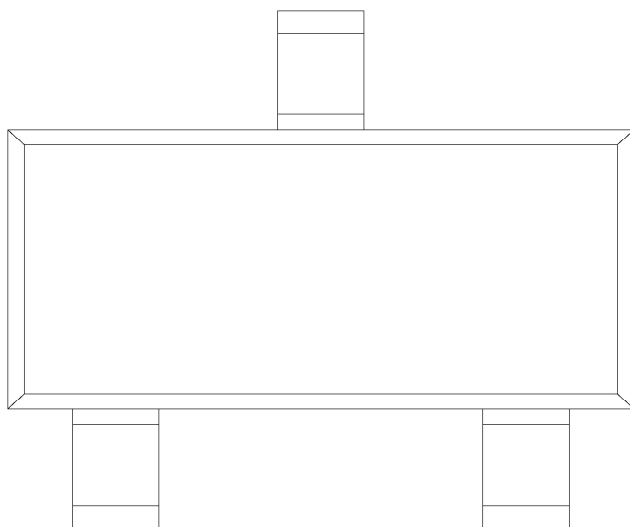
/ Package Dimensions



Dimensions in Millimetres		Symbol		Dimensions in Inches		Symbol	
Max		Min		Max		Min	
12.31		0.45		0.49		0.90	
0.20		0.05		0.05		0.15	
3.20	K	0.05		0.05		0.20	
2.10	M	0.20 MIN				0.70	
1.05	P	7°				6.85	
0.35						0.35	



/ Marking Instructions



说明：

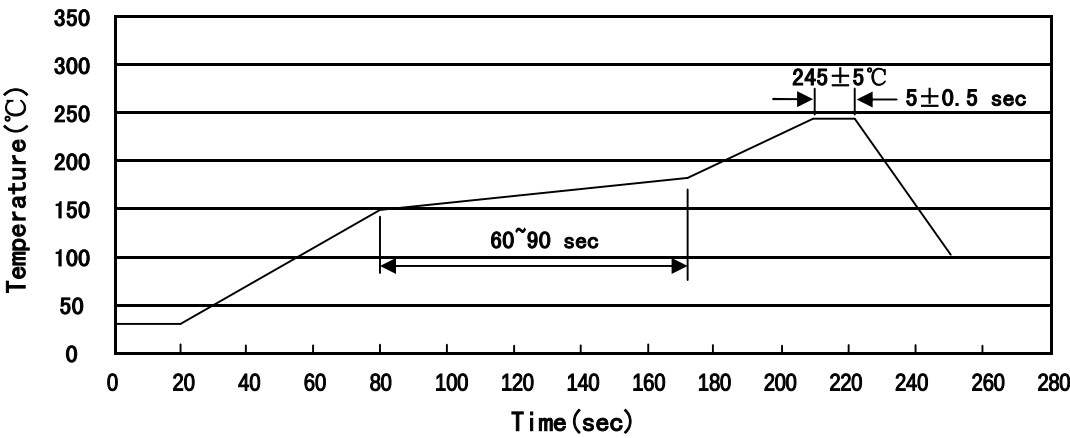
H： 为公司代码

Y2： 为型号代码

B： 为 h_{FE} 分档代码



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 、预热温度 ~ °C，时间 ~ °C
- 、峰值温度 ± °C，时间持续为 ± °C ±
- 、焊接制程冷却速度为 ~ °C °C

/ Resistance to Soldering Heat Test Conditions

温度： ± °C 时间： ± ± °C ±

/ Packaging SPEC.

卷盘包装

	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

/ Notices